

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

<i>In re</i> Application of:	Byung Tai Do, et al.	:	Confirmation No.:	8877
Serial No.:	10/825,910	:	Art Unit:	2818
Filed:	4/16/2004	:	Examiner:	Tu Tu V. Ho
For:	THERMALLY ENHANCED STACKED DIE PACKAGE AND FABRICATION METHOD	:		

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**RESPONSE / AMENDMENT  
TO NON FINAL OFFICE ACTION**

Sir/Madam:

The following Amendment and Remarks are submitted under 37 C.F.R. §1.111 in response to the Office Action mailed February 1, 2006, following the amendment format set forth under 37 CFR §1.121. After this introductory section, there are Amendments to the Claims and then Remarks, each starting on a separate page.

Amendments to the Claims consist of amendments for claims 1, 6, 11, and 16, which are incorporated in a complete listing of the claims.